Product Change Notification - JAON-13CUTO660

Date:

01 Apr 2019

Product Category:

ARCNET-CircLink Controllers

Affected CPNs:

Notification subject:

CCB 3755 Initial Notice: Qualification of MMT as a new assembly site for selected SMSC COM20019I and COM20020I device families available in 28L PLCC (11.5x11.5x4.4mm) package.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.
NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as a new assembly site for selected SMSC COM20019I and COM20020I device families available in 28L PLCC (11.5x11.5x4.4mm) package.

Pre Change:

Assembled at OSE using 1076WA die attach, G631 mold compound and A151 lead frame material with MSL 3 classification.

Post Change:

Assembled at MMT using 3280 die attach, G600V mold compound and A194 lead frame material with MSL 1 classification.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Orient Semiconductor Electronics, Ltd (OSE)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au	Au
Die attach material	1076WA	3280
Molding compound material	G631	G600V
Lead frame material	A151	A194
MSL Classification	MSL3/260C	MSL1/245C

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

May 2019

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and

a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2019				May 2019				
Workweek	14	15	16	17	18	19	20	21	22
Initial PCN Issue Date	X								
Qual Report Availability								X	
Final PCN Issue Date								X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 1, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-13CUTO660_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

COM20019I-DZD
COM20019I-DZD-TR
COM20020I-DZD
COM20020I-DZD-TR

QUALIFICATION PLAN SUMMARY

PCN #: JAON-13CUTO660

Date
Mar 08, 2019

Qualification of MMT as a new assembly site for selected SMSC COM20019I and COM20020I device families available in 28L PLCC (11.5x11.5x4.4mm) package.

Title: Qualification of MMT as a new assembly site for selected SMSC COM20019I and COM20020I device families available in 28L PLCC (11.5x11.5x4.4mm) package.

		Qualification
Misc.	**Assembly site**	MMT
	BD Number	BDM-002089
	MP Code (MPC)	ZG1017L4XA00
	Part Number (CPN)	COM20019I-DZD
	CCB No.	3755
Lead-Frame	**Paddle size**	200x200
	Material	A194
	Surface	Ag Ring Plated
	Process	Stamped
	Lead-lock	No
	Part Number	10102832
	Lead Plating	Matte Tin
Bond Wire	**Material**	Au
Die Attach	**Part Number**	3280
	Conductive	Yes
MC	**Part Number**	G600V
PKG	**PKG Type**	PLCC
	Pin/Ball Count	28
Die	**Die Thickness**	15 mils
	Die Size	129.50x144.50 mils
	MSL	MSL1/245C

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp. 1 lot to be tested 110°C	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1/ 245 °C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C and hot temp. 1 lot to be tested 110°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	+130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. 1 lot to be tested 110°C	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.